

N-Channel Enhancement Mode MOSFET

Features

- 100V/7A,
 R_{DS(ON)} = 18mΩ(max.) @ V_{GS} = 10V
- 100% UIS + R_q Tested
- Reliable and Rugged
- Lead Free and Green Devices Available (RoHS Compliant)

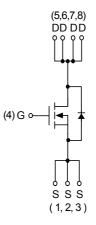
Applications

- DC-DC Converter.
- Secondary Side Synchronous Rectification.

Pin Description

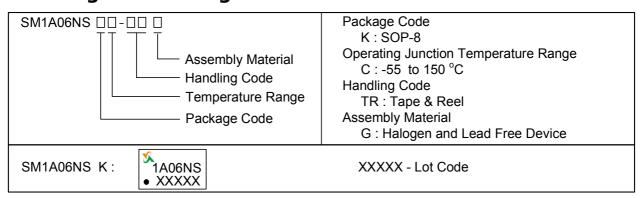


Top View of SOP-8



N-Channel MOSFET

Ordering and Marking Information



Note: SINOPOWER lead-free products contain molding compounds/die attach materials and 100% matte tin plate termination finish; which are fully compliant with RoHS. SINOPOWER lead-free products meet or exceed the lead-free requirements of IPC/JEDEC J-STD-020D for MSL classification at lead-free peak reflow temperature. SINOPOWER defines "Green" to mean lead-free (RoHS compliant) and halogen free (Br or Cl does not exceed 900ppm by weight in homogeneous material and total of Br and Cl does not exceed 1500ppm by weight).

SINOPOWER reserves the right to make changes to improve reliability or manufacturability without notice, and advise customers to obtain the latest version of relevant information to verify before placing orders.



Absolute Maximum Ratings (T_A = 25°C Unless Otherwise Noted)

Symbol	Parameter		Rating	Unit	
Common	Common Ratings				
V _{DSS}	Drain-Source Voltage		100	V	
V _{GSS}	Gate-Source Voltage		±25	\ \ \	
T _J	Maximum Junction Temperature		150	°C	
T _{STG}	Storage Temperature Range		-55 to 150	°C	
Is	Diode Continuous Forward Current	T _A =25°C	2	Α	
	Continuous Drain Current	T _A =25°C	7		
l _D		T _A =70°C	5.6	Α	
I _{DM} ^a	Pulsed Drain Current	T _A =25°C	28	7	
Б	Maximum Davier Discipation	T _A =25°C	1.78	١٨/	
P _D	Maximum Power Dissipation	T _A =70°C	1.14	W	
R _{θJA} ^c	Thermal Resistance-Junction to Ambient	Steady State	70	°C/W	
I _{AS} b	Avalanche Current, Single pulse	L=0.5mH	26	Α	
E _{AS} b	Avalanche Energy, Single pulse	L=0.5mH	169	mJ	

Note a: Pulse width limited by max. junction temperature.

Note b: UIS tested and pulse width limited by maximum junction temperature 150°C (initial temperature Tj=25°C).

Note c : Surface Mounted on 1in² pad area.



Electrical Characteristics (T_A = 25°C Unless Otherwise Noted)

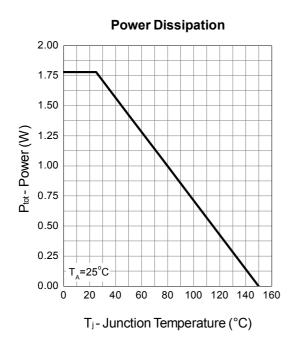
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit	
Static Characteristics							
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _{DS} =250μA	100	-	-	V	
	Zara Cata Valtara Drain Current	V _{DS} =80V, V _{GS} =0V	-	-	1		
I _{DSS}	Zero Gate Voltage Drain Current	T _J =85°C	ate voltage Drain Current	-	-	30	μΑ
V _{GS(th)}	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_{DS}=250\mu A$	2.0	3.0	4.0	V	
I _{GSS}	Gate Leakage Current	V _{GS} =±25V, V _{DS} =0V	-	-	±100	nA	
R _{DS(ON)} d	Drain-Source On-state Resistance	V _{GS} =10V, I _{DS} =7A	-	15	18	mΩ	
Diode Characteristics							
V _{SD} ^d	Diode Forward Voltage	I _{SD} =5A, V _{GS} =0V	-	0.8	1.3	V	
t _{rr}	Reverse Recovery Time	I -0.0 dl /dk-4000/ c	-	44	-	ns	
Q _{rr}	Reverse Recovery Charge	I_{SD} =8A, dI_{SD}/dt =100A/ μ s	-	95	-	nC	
Dynamic Characteristics ^e							
R_{G}	Gate Resistance	V _{GS} =0V,V _{DS} =0V,f=1MHz	-	1.0	-	Ω	
C _{iss}	Input Capacitance	V _{GS} =0V,	-	2100	2730		
C _{oss}	Output Capacitance	V _{DS} =30V,	-	255	-	рF	
C _{rss}	Reverse Transfer Capacitance	Frequency=1.0MHz	-	100	-		
t _{d(ON)}	Turn-on Delay Time		-	19	35		
t _r	Turn-on Rise Time	V_{DD} =30V, R_L =30 Ω ,	-	9	17		
t _{d(OFF)}	Turn-off Delay Time	-I _{DS} =1A, V _{GEN} =10V, $-$ R _G =6 Ω	-	36	65	ns	
t _f	Turn-off Fall Time		-	22	40		
Gate Charge Characteristics ^e							
Qg	Total Gate Charge		-	42	59		
Q_{gs}	Gate-Source Charge	V_{DS} =50V, V_{GS} =10V, V_{DS} =8A	-	12	-	nC	
Q_{gd}	Gate-Drain Charge	7.00	-	12	-		

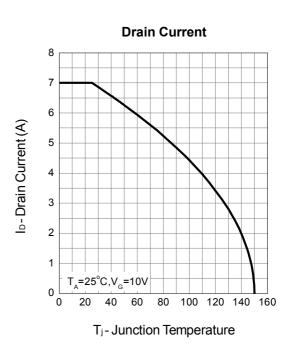
Note d: Pulse test; pulse width≤300μs, duty cycle≤2%.

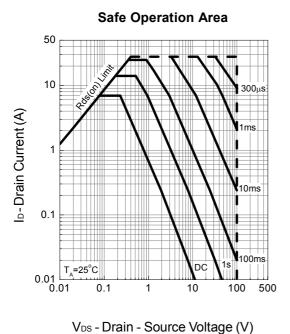
Note e: Guaranteed by design, not subject to production testing.

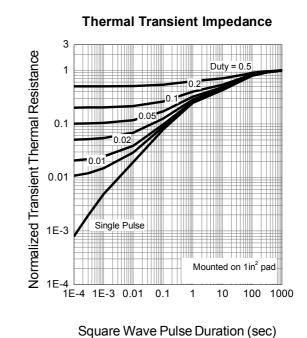


Typical Operating Characteristics





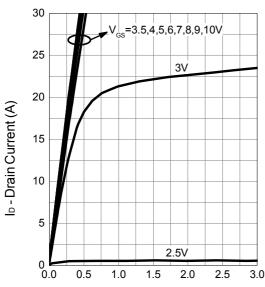






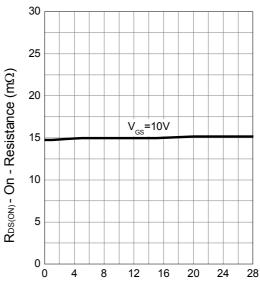
Typical Operating Characteristics (Cont.)

Output Characteristics



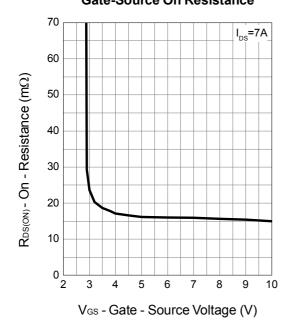
V_{DS}-Drain - Source Voltage (V)

Drain-Source On Resistance

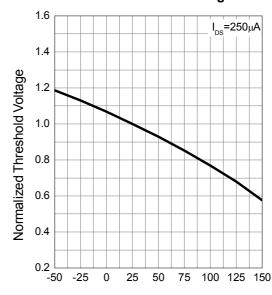


ID-Drain Current (A)

Gate-Source On Resistance



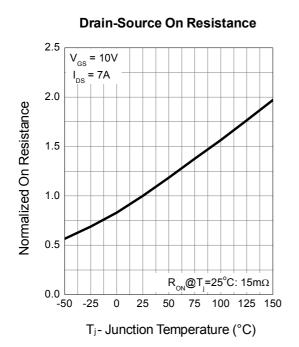
Gate Threshold Voltage

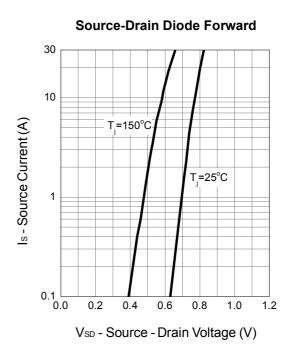


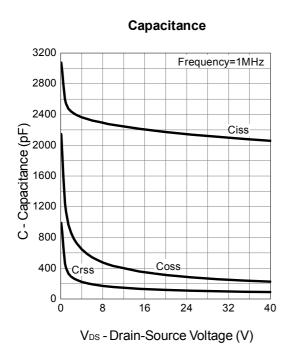
T_j - Junction Temperature (°C)

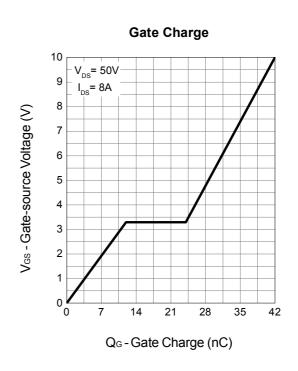


Typical Operating Characteristics (Cont.)



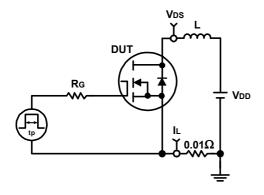


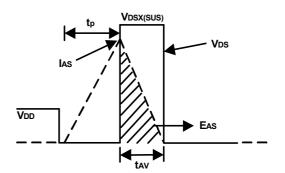




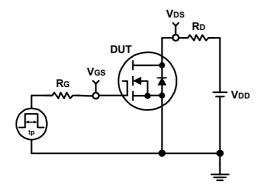


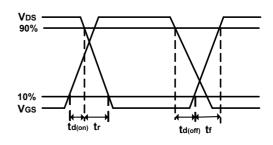
Avalanche Test Circuit and Waveforms





Switching Time Test Circuit and Waveforms







Disclaimer

Sinopower Semiconductor, Inc. (hereinafter "Sinopower") has been making great efforts to development high quality and better performance products to satisfy all customers' needs. However, a product may fail to meet customer's expectation or malfunction for various situations.

All information which is shown in the datasheet is based on Sinopower's research and development result, therefore, Sinopower shall reserve the right to adjust the content and monitor the production.

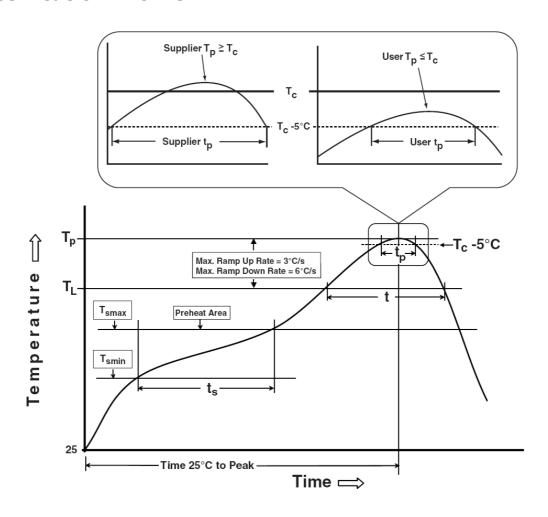
In order to unify the quality and performance, Sinopower has been following JEDEC while defines assembly rule. Notwithstanding all the suppliers basically follow the rule for each product, different processes may cause slightly different results.

The technical information specified herein is intended only to show the typical functions of and examples of application circuits for the products. Sinopower does not grant customers explicitly or implicitly, any license to use or exercise intellectual property or other rights held by Sinopower and other parties. Sinopower shall bear no responsible whatsoever for any dispute arising from the use of such technical information.

The products are not designed or manufactured to be used with any equipment, device or system which requires an extremely high level of reliability, such as the failure or malfunction of which any may result in a direct threat to human life or a risk of human injury. Sinopower shall bear no responsibility in any way for use of any of the products for the above special purposes. If a product is intended to use for any such special purpose, such as vehicle, military, or medical controller relevant applications, please contact Sinopower sales representative before purchasing.



Classification Profile





Classification Reflow Profiles

150 °C 200 °C onds 60-120 seconds
max. 3°C/second max.
217 °C onds 60-150 seconds
emp in table 1 See Classification Temp in table 2
20**
nds 30** seconds
I max. 6 °C/second max.
)(

Table 1. SnPb Eutectic Process – Classification Temperatures (Tc)

Package Thickness	Volume mm³ <350	Volume mm³ ≥350
<2.5 mm	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

Table 2. Pb-free Process – Classification Temperatures (Tc)

Package	Volume mm ³	Volume mm ³	Volume mm ³
Thickness	<350	350-2000	>2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 mm – 2.5 mm	260 °C	250 °C	245 °C
≥2.5 mm	250 °C	245 °C	245 °C

Reliability Test Program

Test item	Method	Description
SOLDERABILITY	JESD-22, B102	5 Sec, 245°C
HTRB	JESD-22, A108	1000 Hrs, 80% of VDS max @ Tjmax
HTGB	JESD-22, A108	1000 Hrs, 100% of VGS max @ Tjmax
PCT	JESD-22, A102	168 Hrs, 100%RH, 2atm, 121°C
TCT	JESD-22, A104	500 Cycles, -65°C~150°C

Customer Service

Sinopower Semiconductor, Inc.

5F, No. 6, Dusing 1St Rd., Hsinchu Science Park,

Hsinchu, 30078, Taiwan

TEL: 886-3-5635818 Fax: 886-3-5635080

^{**} Tolerance for time at peak profile temperature (tp) is defined as a supplier minimum and a user maximum.